Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L^2 - π -MOSV)

2SK2229

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4-V gate drive

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & : RDS\ (ON) = 0.12\ \Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & : |Y_{fs}| = 5.0\ S\ (typ.) \\ \bullet & Low\ leakage\ current & : IDSS = 100\ \mu A\ (max)\ (VDS = 60\ V) \\ \end{array}$

• Enhancement mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	60	V
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	60	V
Gate-source voltage		V_{GSS}	±20	V
Drain current	DC (Note 1)	I _D	5	Α
Diam curient	Pulse (Note 1)	I _{DP}	20	Α
Drain power dissipatio	n	P_{D}	1.3	W
Single pulse avalanche energy (Note 2)		E _{AS}	129	mJ
Avalanche current		I _{AR}	5	Α
Repetitive avalanche energy (Note 3)		E _{AR}	0.13	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C

1.4±0.1 1.05±0.1 1.05±0.1 1.55±0.5 1.50URCE 2.5±0.5 1.SOURCE 2.DRAIN 3.GATE 1.SOURCE 2.DRAIN 3.GATE JEDEC JEITA TOSHIBA 2-8M1B

Weight: 0.54 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R _{th (ch-a)}	96.1	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 7 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

2004-07-06



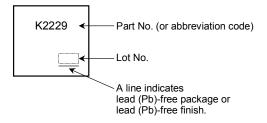
Electrical Characteristics (Ta = 25°C)

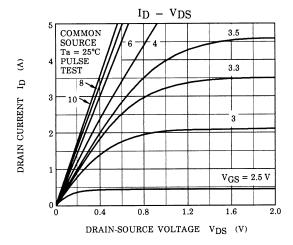
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br voltage	reakdown	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	60	_	ı	V
Gate threshold	/oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source ON resistance	Б	V _{GS} = 4 V, I _D = 1.3 A		0.20	0.30	Ω	
	R _{DS} (ON)	V _{GS} = 10 V, I _D = 2.5 A	_	0.12	0.16		
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	3.0	5.0	_	S
Input capacitano	ce	C _{iss}		_	370	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		60	_	pF
Output capacitance		Coss			180	_	
Switching time	Rise time	t _r	V_{GS} V_{OV} V	_	18	_	
	Turn-on time	t _{on}		l	25	1	ns
	Fall time	t _f		l	55	ı	115
	Turn-off time	t _{off}	$V_{DD} = 30V$ Duty $\leq 1\%$, $t_{W} = 10 \mu s$	l	170	l	
Total gate charge (Gate-source plus gate-drain)		Qg			12	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		8	_	nC
Gate-drain ("miller") charge		Q _{gd}			4	_	

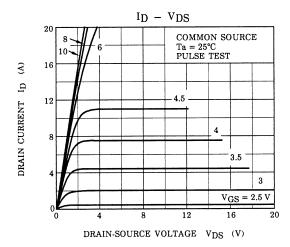
Source-Drain Ratings and Characteristics (Ta = 25°C)

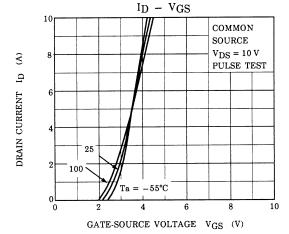
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	20	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V, dI _{DR} /dt = 50 A/μs	1	70		ns
Reverse recovered charge	Q _{rr}		_	0.1	_	μC

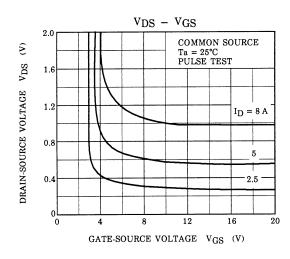
Marking

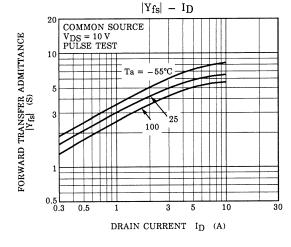


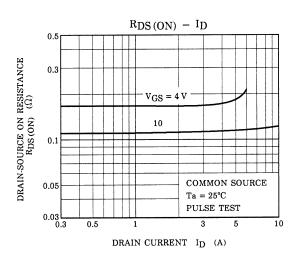


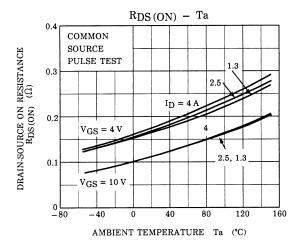


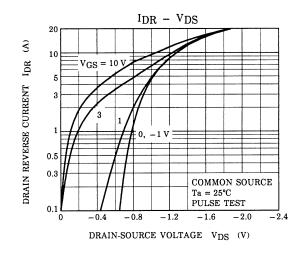


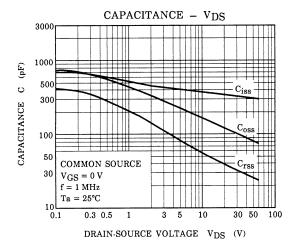


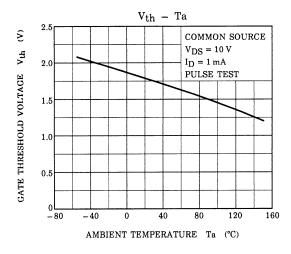


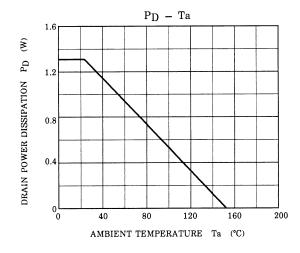


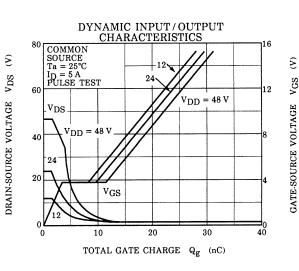




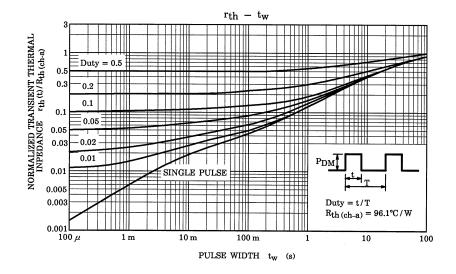


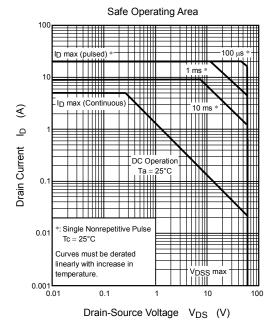


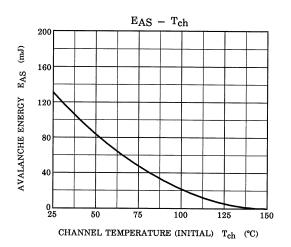


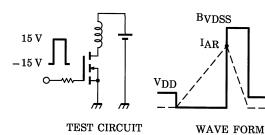


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$$R_G = 25 \Omega$$

 $V_{DD} = 25 V$, $L = 7 mH$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

 v_{DS}

RESTRICTIONS ON PRODUCT USE

Handbook" etc..

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